

# FIVE OUTPUT 3.3V CLOCK BUFFER

IDT2305NZ

## **FEATURES:**

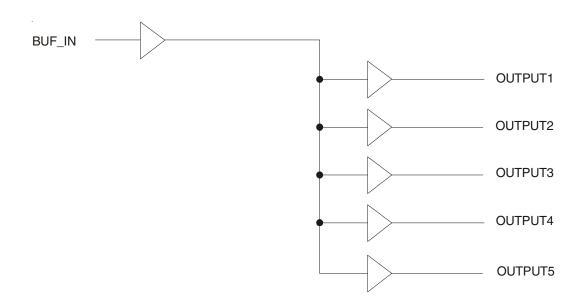
- · One input to five output buffer/driver
- Low power consumption for mobile applications: less than 32mA at 66.6MHz with unloaded outputs
- 8.7ns max input-output delay
- Buffers all frequencies from DC to 133.33MHz
- Output-output skew < 250ps
- 3.3V operation
- · High drive capability
- · Available in SOIC package

## **DESCRIPTION:**

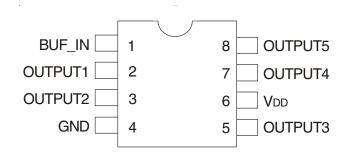
The IDT2305NZ is a low-cost buffer designed to distribute high-speed clocks in mobile PC systems and desktop PC systems. The IDT2305NZ operates at 3.3V with five outputs that can run up to 133.33MHz

The IDT2305NZ is an 8-pin version of the IDT2309NZ. It is designed for low EMI and power optimization and consumes less than 32mA at 66.6MHz, making it ideal for the low power requirements of mobile systems.

## FUNCTIONAL BLOCK DIAGRAM



## **PIN CONFIGURATION**



SOIC TOP VIEW

# ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max.	Unit
VDD	Supply Voltage Range	-0.5 to +4.6	٧
V <sub>I</sub> <sup>(2)</sup>	Input Voltage Range (REF)	-0.5 to +5.5	٧
Vı	Input Voltage Range	-0.5 to	٧
	(except REF)	VDD+0.5	
IIK (VI < 0)	Input Clamp Current	<b>-</b> 50	mA
Io (Vo = 0 to VDD)	Continuous Output Current	±50	mA
VDD or GND	Continuous Current	±100	mA
Ta = 55°C	Maximum Power Dissipation	0.7	W
(in still air)(3)			
Tstg	Storage Temperature Range	-65 to +150	°C
Operating	Commercial Temperature	0 to +70	°C
Temperature	Range		
Operating	Industrial Temperature	-40 to +85	°C
Temperature	Range		

### NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

## PIN DESCRIPTION

Pin Name	Pin Number	Functional Description
Vdd	6	3.3V Digital Voltage Supply
GND	4	Ground
BUF_IN	1	Inputclock
OUTPUT[1:5]	2, 3, 6, 7, 10	Outputs

# OPERATING CONDITIONS - COMMERCIAL

Symbol	Parameter	Min.	Max.	Unit
VDD	Supply Voltage	3	3.6	V
TA	TA Operating Temperature (Ambient Temperature)		70	°C
CL	Load Capacitance, Fout < 100MHz	_	30	pF
	Load Capacitance 100MHz < Fout < 133.33MHz	_	15	
Cin	Input Capacitance	_	7	pF
BUF_IN, OUTPUT[1:5]	Operating Frequency	DC	133.33	MHz

# OPERATING CONDITIONS - INDUSTRIAL

Symbol	Parameter	Min.	Max.	Unit
VDD	Supply Voltage	3	3.6	V
TA	A Operating Temperature (Ambient Temperature)		+85	°C
CL Load Capacitance, Fouт < 100MHz		_	30	pF
	Load Capacitance 100MHz < Fout < 133.33MHz	_	15	
Cin	Input Capacitance	_	7	pF
BUF_IN, OUTPUT[1:5]	Operating Frequency	DC	133.33	MHz

# DC ELECTRICAL CHARACTERISTICS - COMMERCIAL

Symbol	Parameter	Conditions	Min.	Max.	Unit
VIL	Input LOW Voltage(1)		_	0.8	V
VIH	Input HIGH Voltage(1)		2	_	V
lıL	Input LOW Current	Vin = 0V	_	50	μΑ
lih	Input HIGH Current	VIN = VDD	_	100	μΑ
Vol	Output LOW Voltage(2)	IoL = 12mA	_	0.4	V
Voн	Output HIGH Voltage(2)	Iон = -12mA	2.4	_	V
IDD	Supply Current	Unloaded Outputs at 66.66MHz	1	32	mA

### NOTES:

- 1. BUF\_IN input has a threshold voltage of VDD/2.
- 2. Parameter is guaranteed by design but not production tested.

## DC ELECTRICAL CHARACTERISTICS - INDUSTRIAL

Symbol	Parameter	Conditions	Min.	Max.	Unit
VIL	Input LOW Voltage <sup>(1)</sup>		_	0.8	V
VIH	Input HIGH Voltage(1)		2	_	V
lıL	Input LOW Current	VIN = 0V	_	50	μΑ
Іін	Input HIGH Current	VIN = VDD	_	100	μΑ
Vol	Output LOW Voltage(2)	IoL = 12mA	_	0.4	V
Vон	Output HIGH Voltage(2)	Iон = -12mA	2.4	_	V
IDD	Supply Current	Unloaded Outputs at 66.66MHz	_	35	mA

### NOTES:

- 1. BUF\_IN input has a threshold voltage of VDD/2.
- 2. Parameter is guaranteed by design but not production tested.

# SWITCHING CHARACTERISTICS - COMMERCIAL (1)

Symbol	Parameter <sup>(2)</sup>	Conditions	Min.	Тур.	Max.	Unit
ts	Rise Time	Measured between 0.8V and 2V	-	_	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	_	1.5	ns
<b>t</b> 5	Output to Output Skew	All outputs equally loaded	-	_	250	ps
t6	Propagation Delay, BUF_IN Rising Edge to OUTPUT Rising Edge	Measured at VDD/2	1	5	8.7	ns
DC	Duty Cycle	Measured at VDD/2	45	_	55	%

### NOTES:

- 1. All parameters specified with loaded outputs.
- 2. Parameter is guaranteed by design but not production tested.

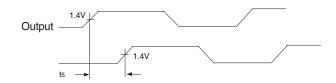
# SWITCHING CHARACTERISTICS - INDUSTRIAL (1)

Symbol	Parameter <sup>(2)</sup>	Conditions	Min.	Тур.	Max.	Unit
t3	Rise Time	Measured between 0.8V and 2V			1.5	ns
t4	FallTime	Measured between 0.8V and 2V			1.5	ns
t5	Output to Output Skew	All outputs equally loaded	_		250	ps
t6	Propagation Delay, BUF_IN Rising Edge to OUTPUT Rising Edge	Measured at VDD/2	1	5	8.7	ns
DC	Duty Cycle	Measured at VDD/2	45	_	55	%

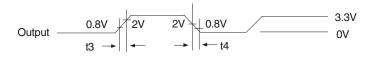
#### NOTES:

- 1. All parameters specified with loaded outputs.
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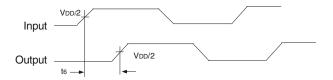
# **SWITCHING WAVEFORMS**



Output to Output Skew

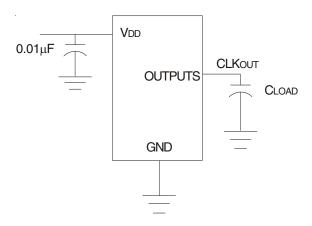


All Outputs Rise/Fall Time

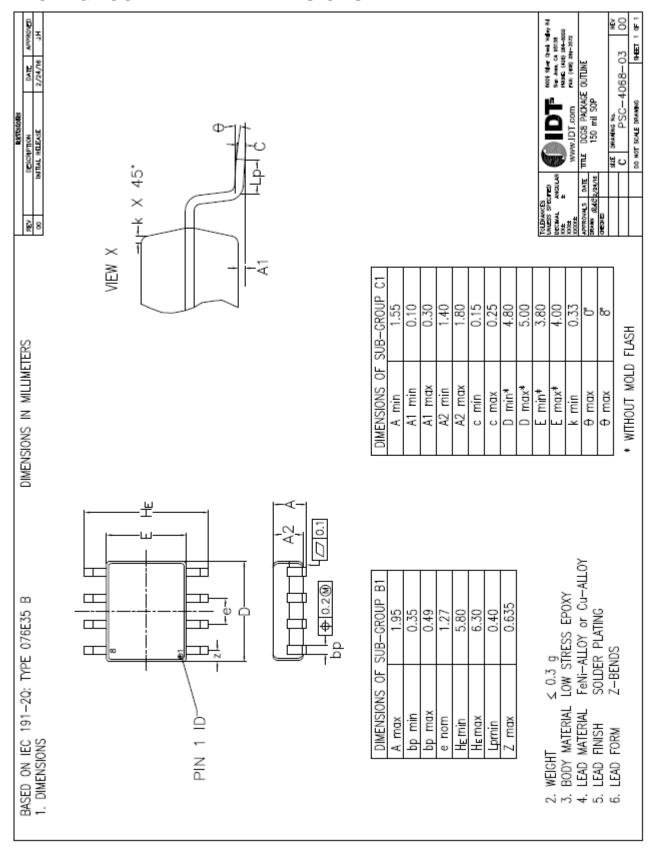


Input to Output Propagation Delay

# **TEST CIRCUIT**



# PACKAGE OUTLINE AND DIMENSIONS



# **ORDERING INFORMATION**

Part / Order Number	Shipping Packaging	Package	Temperature
2305NZ-1HDCG	Tubes	8-pin SOIC	0 to +70°
2305NZ-1HDCG8	Tape and Reel	8-pin SOIC	0 to +70°
2305NZ-1HDCGI	Tubes	8-pin SOIC	-40 to +85°
2305NZ-1HDCGI8	Tape and Reel	8-pin SOIC	-40 to +85°

<sup>&</sup>quot;G" after the two-letter package code denotes Pb-free configuration, RoHS compliant

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